

## SOLDERING CONDITIONS 焊接条件

### 1. Soldering with a soldering iron

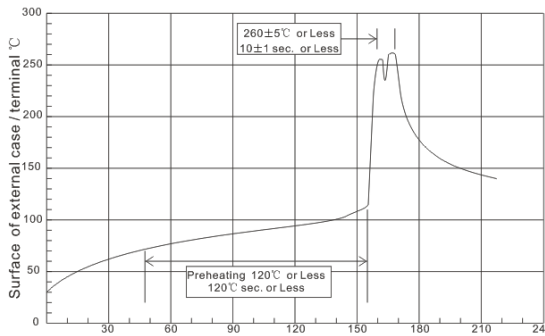
#### 1.1. Soldering condition should be under the following ranges.

	Soldering iron temperature	time
Soldering condition	400±10℃	Within 5S.

- 1.2. When the lead terminal for radial lead type must be processed because the lead pitch and the PCB holes in spacing do not match, process it without any stresses to GPCAP before soldering.
- 1.3. Soldering without any excessive stresses to GPCAP itself.
- 1.4. When an GPCAP has been soldered once and needs to be removed, remove it after the solder has been completely melted.
- 1.5. Do not let the tip of the soldering iron touch the GPCAP itself.

### 2. Flow soldering

#### 2.1. Soldering condition should be under the following ranges.



Recommended flow soldering condition

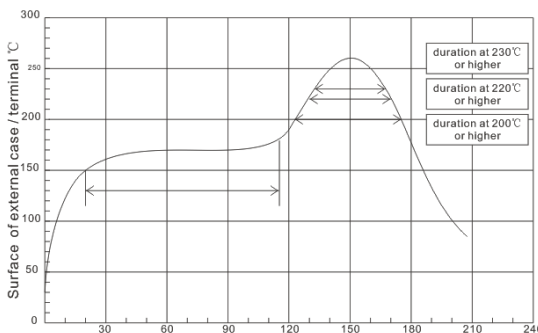
	Temperature	Time	Flow number
Preheating	120℃ or less (ambient temperature)	120 sec. or less	1 time
Soldering condition	260±5℃ or less	10+1 sec. or less	2 times or less

※:When soldering 1 times, immersion time should be 10±1℃ sec. or less.

- 2.2. Do not apply flow soldering to SMD type.
- 2.3. Do not solder GPCAP itself by submerging it in melted solder. Solder the opposite side that the GPCAP is mounted on.
- 2.4. Note that flux does not adhere to anywhere expect the lead terminal.
- 2.5. Note that other components do not fall over and touch the GPCAP when soldering.

### 3. Reflow soldering

#### 3.1. Soldering condition should be under the following ranges.



Recommended flow soldering condition

	Conductive polymer electrolyte SMD type	
Peak temperature (Max.)	250℃	260℃
Preheat	150℃ to 180℃, 90±30 sec.	
200℃ over time (Max.)	60 sec.	60 sec.
220℃ over time (Max.)	50 sec.	50 sec.
230℃ over time (Max.)	40 sec.	40 sec.
Reflow number	Twice or less	Only 1 time

- 3.2. Do not apply reflow soldering to Radial lead type.
- 3.3. Please contact us for setting VPS condition.

### 1. 电烙铁焊接

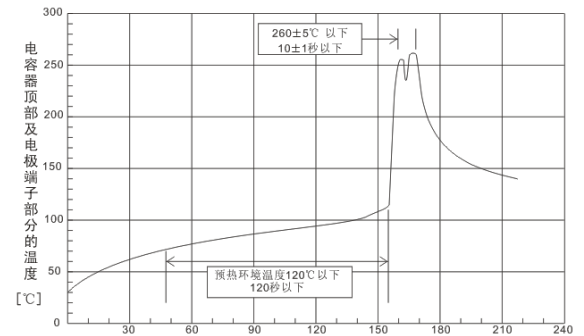
#### 1.1. 请在以下焊接条件（温度、时间）范围内使用。

	电烙铁温度	焊接时间
焊接条件	400±10℃	5秒钟内

- 1.2. 焊接插装时，若引线端子间距和印刷电路板孔间距不符而需要修正引线端子时，应在焊接前避免对固态铝电解电容本体施加应力的情况下修整。
- 1.3. 使用电烙铁焊接时，注意不要对固态铝电解电容本体施加过度应力。
- 1.4. 焊接后需要卸下固体铝电解电容、修正焊接状态时，应先充分熔化焊料，防止对固体铝电解电容的引线端子施加应力。
- 1.5. 电烙铁头不得接触固体铝电解电容本体。

### 2. 波峰焊接条件

#### 2.1. 请在以下焊接条件（温度、时间）范围内使用。



波峰焊推荐条件:

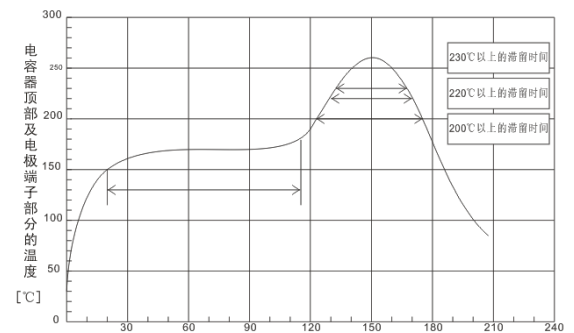
	温度	时间	次数
预热	120℃以下 (环境温度)	120秒以内	1次
焊接条件	260±5℃以下	10+1秒以内	2次以下

※当2次焊接时，焊料的浸渍时间合计为10+1秒以下。

- 2.2. 贴装型固态铝电解电容器不适用于波峰焊。
- 2.3. 不要将固态铝电解电容浸渍在溶解焊料中。焊接部位只限于印刷板上与固态电容相反的一侧。
- 2.4. 助焊剂不要贴附在电极端子以外的部位。
- 2.5. 焊接时，注意不要碰到其它元件，以免碰触固态电容。

### 3. 回流焊条件

#### 3.1. 请在以下焊接条件（温度、时间）范围内使用。



回流焊推荐条件:

	贴片型固态铝电解电容	
最高温度	250℃	260℃
预热	150℃~180℃, 90±30秒	
200℃以上的滞留时间	60秒	60秒
220℃以上的滞留时间	50秒	50秒
230℃以上的滞留时间	40秒	40秒
回流焊次数	2次以下	1次

- 3.2. 不要对插装品（DIP）进行回流焊。
- 3.3. 使用VPS焊接时，请先联系我们。